

# GANE1R8-100QBA

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

13 March 2025

Product data sheet

## 1. General description

The GANE1R8-100QBA is a general purpose 100 V, 1.8 mΩ Gallium Nitride (GaN) FET in a Very-Thin-Profile Quad Flat No-Lead Package (VQFN) package. It is a normally-off e-mode device offering superior performance and very low on-state resistance.

## 2. Features and benefits

- Enhancement mode - normally-off power switch
- Ultra high frequency switching capability
- No body diode
- Low gate charge, low output charge
- Qualified for standard applications
- RoHS, Pb-free, REACH-compliant
- High efficiency and high power density
- Very-Thin-Profile Quad Flat No-Lead Package (VQFN) 4.0 mm x 6.0 mm

## 3. Applications

- High power density and high efficiency power conversion
- AC-to-DC converters, (secondary stage)
- High frequency DC-to-DC converters in 48 V systems
- Fast battery charging, mobile phone, laptop, tablet and USB type-C chargers
- Datacom and telecom (AC-to-DC and DC-to-DC) converters
- Motor drives
- LiDAR (non-automotive)
- Class D audio amplifiers

## 4. Quick reference data

Table 1. Quick reference data

| Symbol                        | Parameter                        | Conditions                                                                             |     | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|----------------------------------------------------------------------------------------|-----|-----|-----|-----|------|
| $V_{DS}$                      | drain-source voltage             | $-40\text{ °C} \leq T_j \leq 150\text{ °C}$                                            |     | -   | -   | 100 | V    |
| $I_D$                         | drain current                    | $V_{GS} = 5\text{ V}; T_{mb} = 25\text{ °C}$                                           | [1] | -   | -   | 100 | A    |
| $P_{tot}$                     | total power dissipation          | $T_{mb} = 25\text{ °C}$ ; Fig. 1                                                       |     | -   | -   | 65  | W    |
| $T_j$                         | junction temperature             |                                                                                        |     | -40 | -   | 150 | °C   |
| <b>Static characteristics</b> |                                  |                                                                                        |     |     |     |     |      |
| $R_{DSon}$                    | drain-source on-state resistance | $V_{GS} = 5\text{ V}; I_D = 40\text{ A}; T_j = 25\text{ °C}$ ; Fig. 8; Fig. 9; Fig. 10 |     | -   | 1.4 | 1.8 | mΩ   |
|                               |                                  | $V_{GS} = 5\text{ V}; I_D = 40\text{ A}; T_j = 150\text{ °C}$ ; Fig. 8; Fig. 11        |     | -   | 2.8 | -   | mΩ   |
| $R_G$                         | gate resistance                  | $f = 5\text{ MHz}$ ; open drain                                                        |     | -   | 1.8 | -   | Ω    |

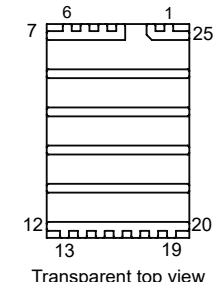
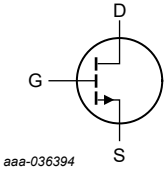
100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

| Symbol                  | Parameter         | Conditions                                                            |     | Min | Typ | Max | Unit |
|-------------------------|-------------------|-----------------------------------------------------------------------|-----|-----|-----|-----|------|
| Dynamic characteristics |                   |                                                                       |     |     |     |     |      |
| Q <sub>GD</sub>         | gate-drain charge | I <sub>D</sub> = 40 A; V <sub>DS</sub> = 50 V; V <sub>GS</sub> = 5 V; |     | -   | 4.5 | -   | nC   |
| Q <sub>G(tot)</sub>     | total gate charge | T <sub>j</sub> = 25 °C; Fig. 12; Fig. 13                              |     | -   | 22  | -   | nC   |
| Q <sub>oss</sub>        | output charge     | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; Fig. 16                | [2] | -   | 125 | -   | nC   |

- [1] Limited by package
- [2] Q<sub>r</sub> is not specified separately from Q<sub>oss</sub> for e-mode GaN FETs, since Q<sub>r</sub> = Q<sub>oss</sub> + Q<sub>D</sub>, and Q<sub>D</sub> = 0. (Q<sub>D</sub> is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q<sub>oss</sub> have to be transferred for e-mode GaN FETs.)

5. Pinning information

Table 2. Pinning information

| Pin    | Symbol | Description | Simplified outline                                                                                                              | Graphic symbol                                                                                    |
|--------|--------|-------------|---------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------|
| 1,2,25 | G      | gate        | <br>Transparent top view<br>VQFN7 (SOT8091-1) | <br>aaa-036394 |
| 12-20  | D      | drain       |                                                                                                                                 |                                                                                                   |
| 21,23  | S      | source      |                                                                                                                                 |                                                                                                   |
| 22,24  | D      | drain       |                                                                                                                                 |                                                                                                   |
| 3-7    | S      | source      |                                                                                                                                 |                                                                                                   |
| 8,10   | D      | drain       |                                                                                                                                 |                                                                                                   |
| 9,11   | S      | source      |                                                                                                                                 |                                                                                                   |

6. Ordering information

Table 3. Ordering information

| Type number   | Package |                                   |           |
|---------------|---------|-----------------------------------|-----------|
|               | Name    | Description                       | Version   |
| GAN1R8-100QBA | VQFN7   | very thin quad flatpack; no leads | SOT8091-1 |

7. Marking

Table 4. Marking codes

| Type number   | Marking code |
|---------------|--------------|
| GAN1R8-100QBA | 1R8DQBA      |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter               | Conditions                                                       |     | Min | Max | Unit |
|------------------|-------------------------|------------------------------------------------------------------|-----|-----|-----|------|
| V <sub>DS</sub>  | drain-source voltage    | -40 °C ≤ T <sub>j</sub> ≤ 150 °C                                 |     | -   | 100 | V    |
| V <sub>GS</sub>  | gate-source voltage     |                                                                  |     | -4  | 6   | V    |
| P <sub>tot</sub> | total power dissipation | T <sub>mb</sub> = 25 °C; Fig. 1                                  |     | -   | 65  | W    |
| I <sub>D</sub>   | drain current           | V <sub>GS</sub> = 5 V; T <sub>mb</sub> = 25 °C                   | [1] | -   | 100 | A    |
| I <sub>DM</sub>  | peak drain current      | pulsed; t <sub>p</sub> = 100 μs; T <sub>mb</sub> = 25 °C; Fig. 2 |     | -   | 320 | A    |

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

| Symbol              | Parameter                  | Conditions |  | Min | Max | Unit |
|---------------------|----------------------------|------------|--|-----|-----|------|
| T <sub>stg</sub>    | storage temperature        |            |  | -40 | 150 | °C   |
| T <sub>j</sub>      | junction temperature       |            |  | -40 | 150 | °C   |
| T <sub>sld(M)</sub> | peak soldering temperature |            |  | -   | 260 | °C   |

[1] Limited by package

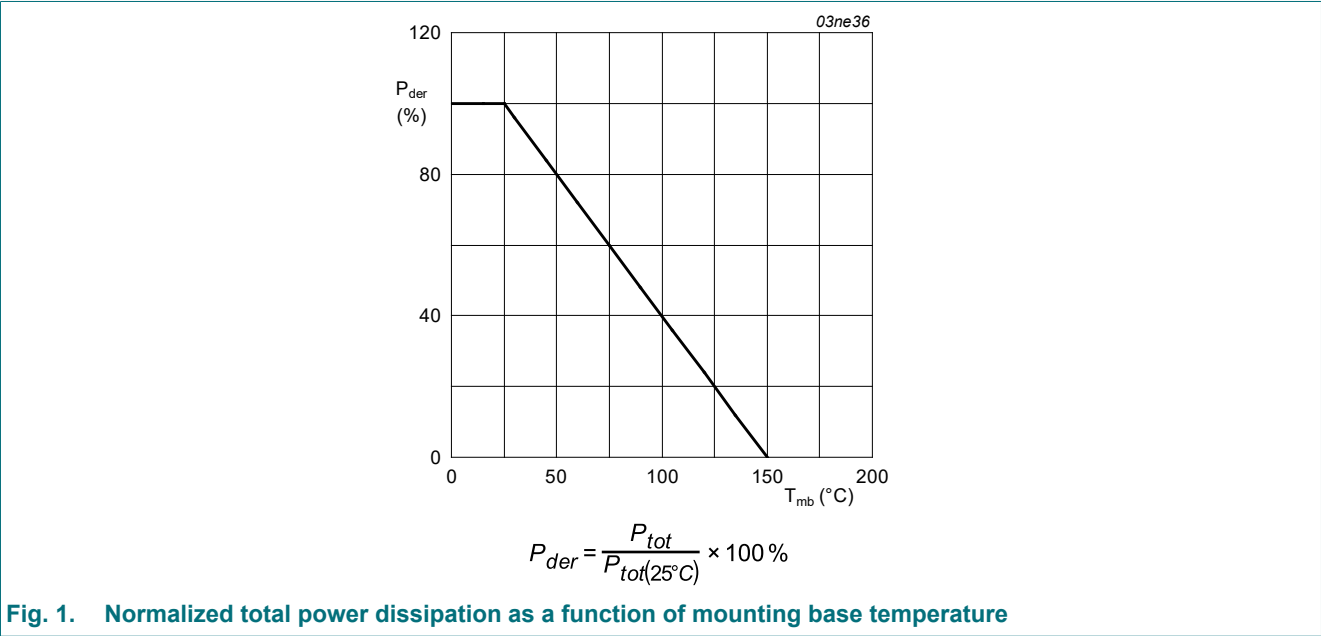


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

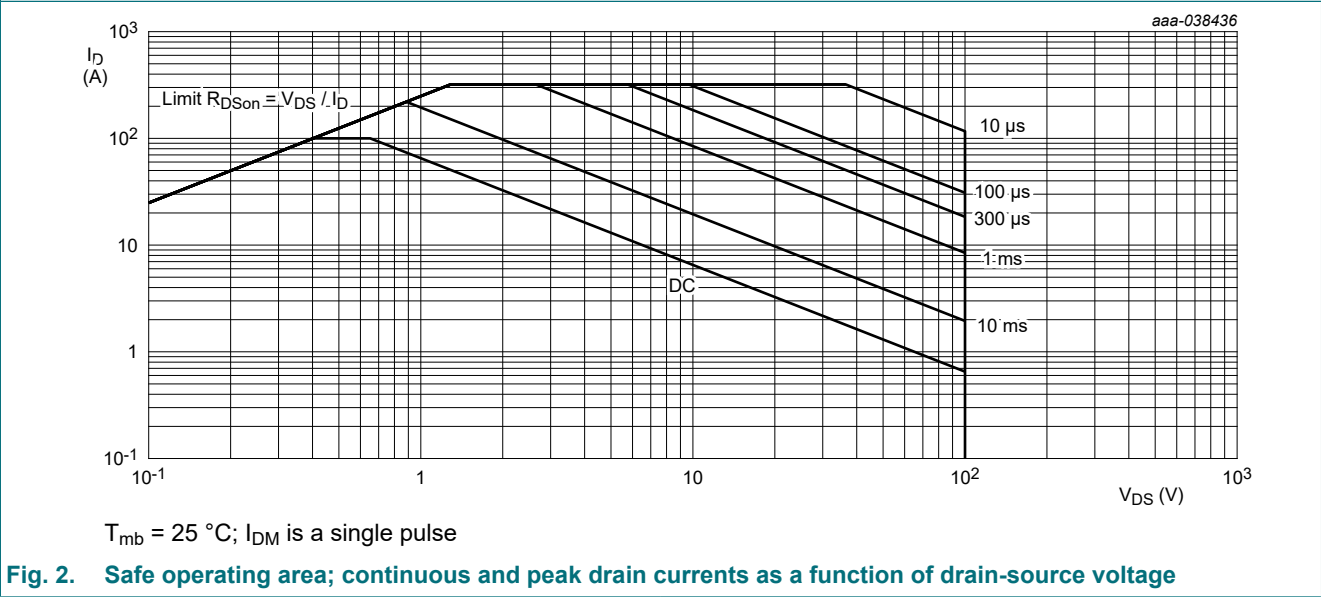


Fig. 2. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

## 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol               | Parameter                                | Conditions |  | Min | Typ | Max   | Unit |
|----------------------|------------------------------------------|------------|--|-----|-----|-------|------|
| R <sub>th(j-c)</sub> | thermal resistance from junction to case |            |  | -   | -   | 13.96 | K/W  |

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

| Symbol         | Parameter                                         | Conditions |     | Min | Typ | Max   | Unit |
|----------------|---------------------------------------------------|------------|-----|-----|-----|-------|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | Fig. 3     |     | -   | -   | 1.92  | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient       |            | [1] | -   | -   | 57.56 | K/W  |

[1]  $R_{th(j-a)}$  is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board.

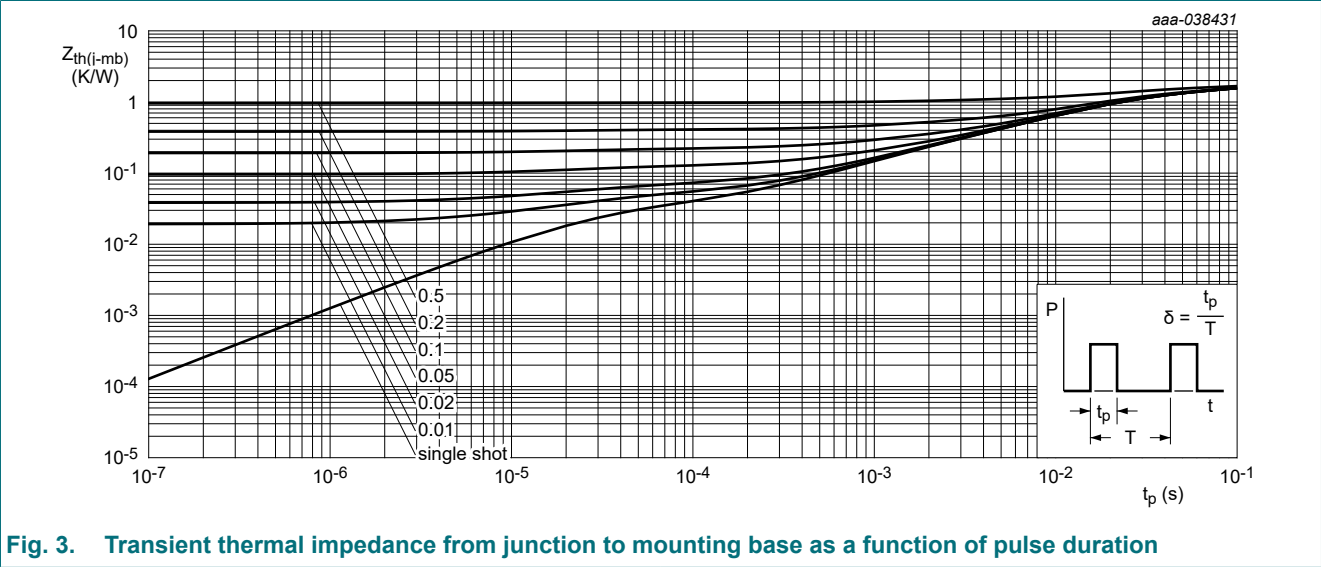


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

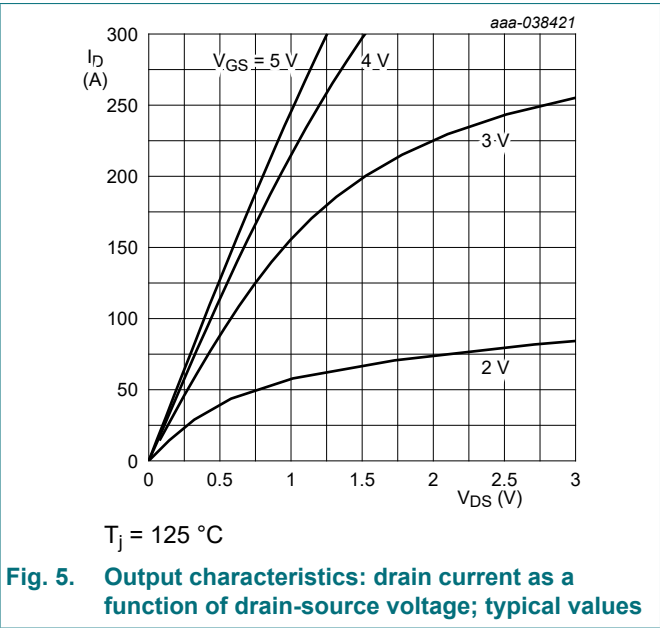
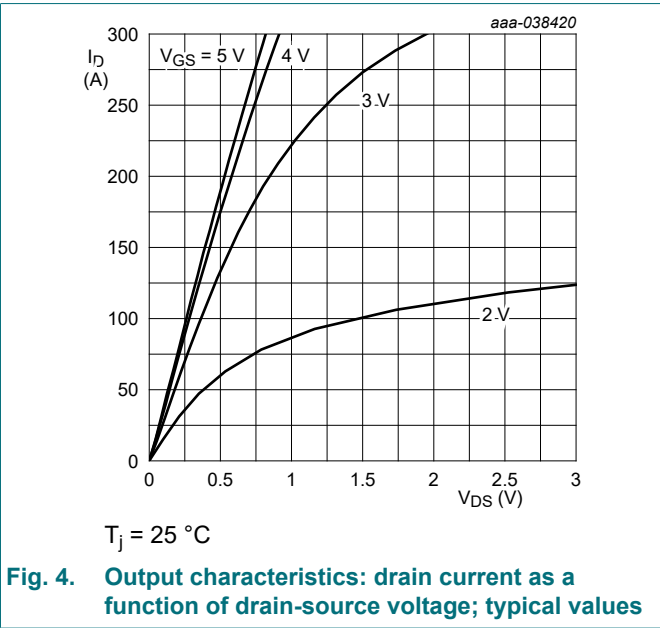
Table 7. Characteristics

| Symbol                  | Parameter                        | Conditions                                                                                                                   |  | Min | Typ | Max  | Unit          |
|-------------------------|----------------------------------|------------------------------------------------------------------------------------------------------------------------------|--|-----|-----|------|---------------|
| Static characteristics  |                                  |                                                                                                                              |  |     |     |      |               |
| $V_{GS(th)}$            | gate-source threshold voltage    | $I_D = 21\text{ mA}$ ; $V_{DS}=V_{GS}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; Fig. 7                                         |  | 0.8 | 1.1 | 2.5  | V             |
|                         |                                  | $I_D = 21\text{ mA}$ ; $V_{DS}=V_{GS}$ ; $T_j = 150\text{ }^{\circ}\text{C}$ ; Fig. 7                                        |  | -   | 1   | -    | V             |
| $I_{DSS}$               | drain leakage current            | $V_{DS} = 80\text{ V}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = 25\text{ }^{\circ}\text{C}$                                          |  | -   | 9.5 | 93   | $\mu\text{A}$ |
| $I_{GSS}$               | gate leakage current             | $V_{GS} = 5\text{ V}$ ; $V_{DS} = 0\text{ V}$ ; $T_j = 25\text{ }^{\circ}\text{C}$                                           |  | -   | 2.8 | 55   | $\mu\text{A}$ |
|                         |                                  | $V_{GS} = 5\text{ V}$ ; $V_{DS} = 0\text{ V}$ ; $T_j = 125\text{ }^{\circ}\text{C}$                                          |  | -   | 136 | 2700 | $\mu\text{A}$ |
|                         |                                  | $V_{GS} = -4\text{ V}$ ; $V_{DS} = 0\text{ V}$ ; $T_j = 25\text{ }^{\circ}\text{C}$                                          |  | -   | 0.3 | 1.2  | $\mu\text{A}$ |
| $R_{DSon}$              | drain-source on-state resistance | $V_{GS} = 5\text{ V}$ ; $I_D = 40\text{ A}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; Fig. 8; Fig. 9; Fig. 10                   |  | -   | 1.4 | 1.8  | m $\Omega$    |
|                         |                                  | $V_{GS} = 5\text{ V}$ ; $I_D = 40\text{ A}$ ; $T_j = 150\text{ }^{\circ}\text{C}$ ; Fig. 8; Fig. 11                          |  | -   | 2.8 | -    | m $\Omega$    |
| $R_G$                   | gate resistance                  | $f = 5\text{ MHz}$ ; open drain                                                                                              |  | -   | 1.8 | -    | $\Omega$      |
| Dynamic characteristics |                                  |                                                                                                                              |  |     |     |      |               |
| $Q_{G(tot)}$            | total gate charge                | $I_D = 40\text{ A}$ ; $V_{DS} = 50\text{ V}$ ; $V_{GS} = 5\text{ V}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; Fig. 12; Fig. 13 |  | -   | 22  | -    | nC            |
| $Q_{GS}$                | gate-source charge               |                                                                                                                              |  | -   | 4.5 | -    | nC            |
| $Q_{GD}$                | gate-drain charge                |                                                                                                                              |  | -   | 4.5 | -    | nC            |

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

| Symbol                       | Parameter                                    | Conditions                                                                                                                                                                   |     | Min | Typ  | Max | Unit |
|------------------------------|----------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----|------|-----|------|
| C <sub>iss</sub>             | input capacitance                            | V <sub>DS</sub> = 50 V; V <sub>GS</sub> = 0 V; f = 100 kHz;<br>T <sub>j</sub> = 25 °C; <a href="#">Fig. 14</a>                                                               |     | -   | 2500 | -   | pF   |
| C <sub>oss</sub>             | output capacitance                           |                                                                                                                                                                              |     | -   | 1100 | -   | pF   |
| C <sub>rss</sub>             | reverse transfer capacitance                 |                                                                                                                                                                              |     | -   | 19   | -   | pF   |
| C <sub>o(er)</sub>           | effective output capacitance, energy related | V <sub>DS</sub> = 50 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 15</a>                                                                               | [1] | -   | 1700 | -   | pF   |
| C <sub>o(tr)</sub>           | effective output capacitance, time related   | V <sub>DS</sub> = 50 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                                                                        | [2] | -   | 2500 | -   | pF   |
| Q <sub>oss</sub>             | output charge                                | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; <a href="#">Fig. 16</a>                                                                                                       | [3] | -   | 125  | -   | nC   |
| Source-drain characteristics |                                              |                                                                                                                                                                              |     |     |      |     |      |
| V <sub>SD</sub>              | source-drain voltage                         | I <sub>S</sub> = 0.5 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 17</a> ; <a href="#">Fig. 18</a> ; <a href="#">Fig. 19</a> ; <a href="#">Fig. 20</a> |     | -   | 1.5  | -   | V    |

- [1] C<sub>O(er)</sub> is the fixed capacitance that gives the same stored energy as C<sub>OSS</sub> while V<sub>DS</sub> is rising from 0 to 50 V
- [2] C<sub>O(tr)</sub> is the fixed capacitance that gives the same charging time as C<sub>OSS</sub> while V<sub>DS</sub> is rising from 0 to 50 V
- [3] Q<sub>r</sub> is not specified separately from Q<sub>oss</sub> for e-mode GaN FETs, since Q<sub>r</sub> = Q<sub>oss</sub> + Q<sub>D</sub>, and Q<sub>D</sub> = 0. (Q<sub>D</sub> is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q<sub>oss</sub> have to be transferred for e-mode GaN FETs.)



100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

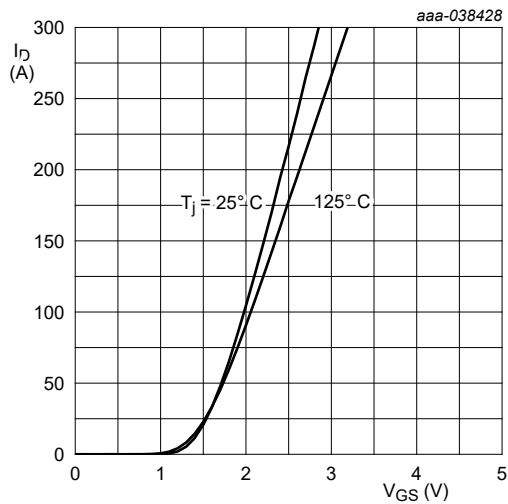


Fig. 6. Transfer characteristics; drain current as a function of gate-source voltage; typical values

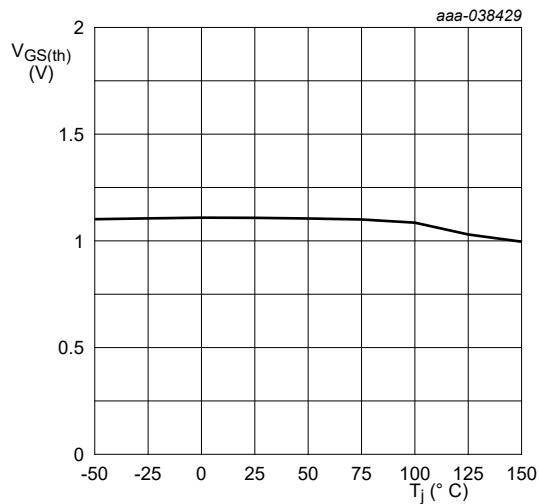


Fig. 7. Gate-source threshold voltage as a function of junction temperature; typical values

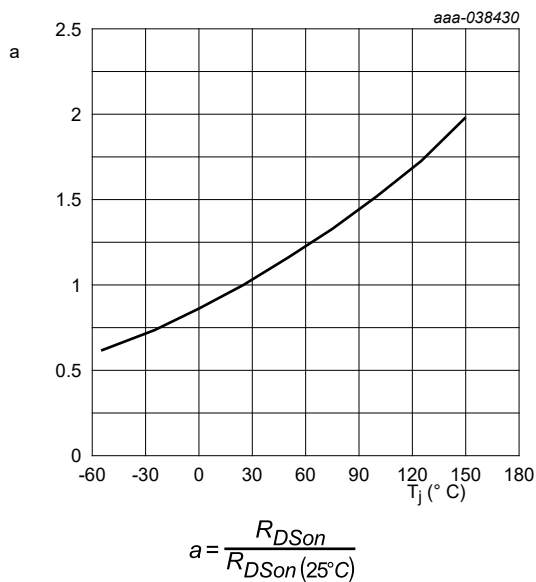


Fig. 8. Normalized drain-source on-state resistance factor as a function of junction temperature

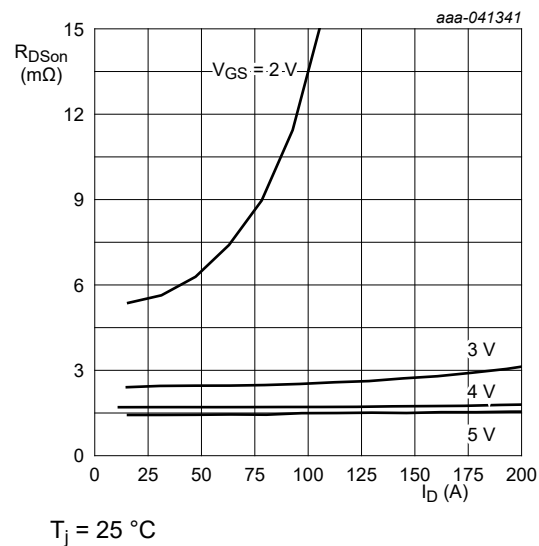


Fig. 9. Drain-source on-state resistance as a function of drain current ; typical values

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

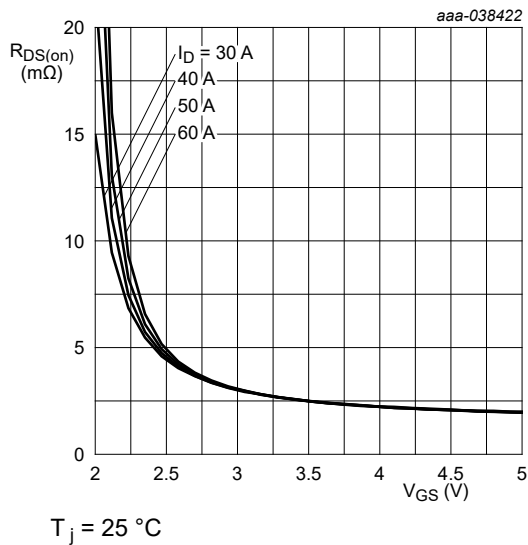


Fig. 10. Drain-source on-state resistance as a function of gate-source voltage; typical values

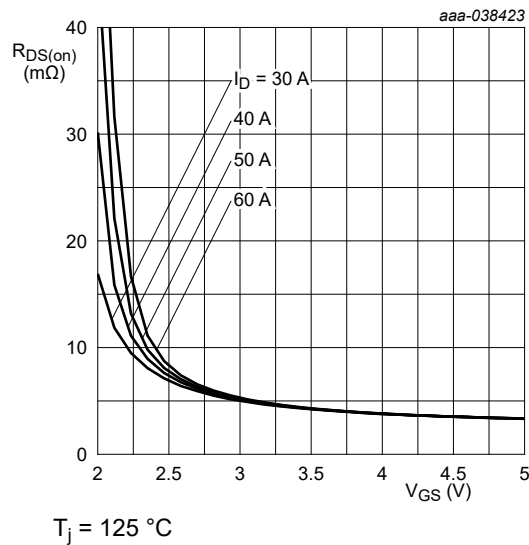


Fig. 11. Drain-source on-state resistance as a function of gate-source voltage; typical values

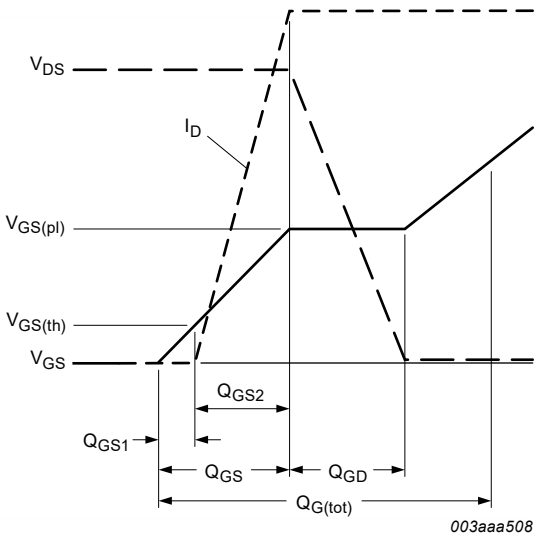


Fig. 12. Gate charge waveform definitions

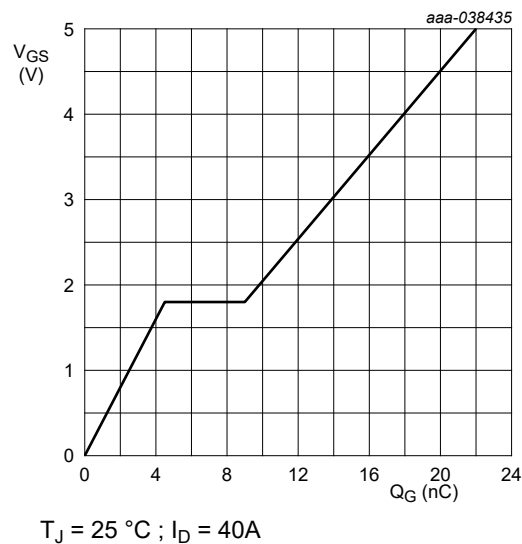


Fig. 13. Gate-source voltage as a function of gate charge; typical values

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

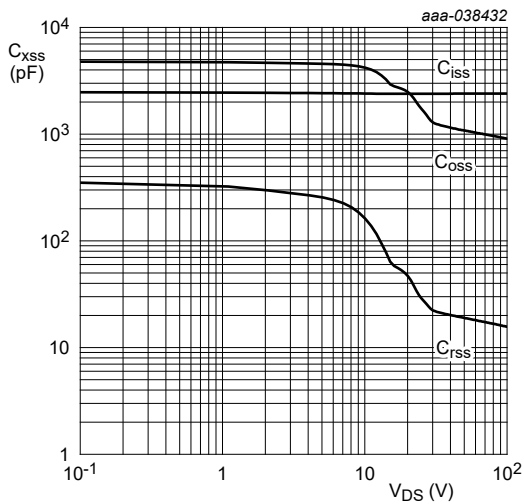


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

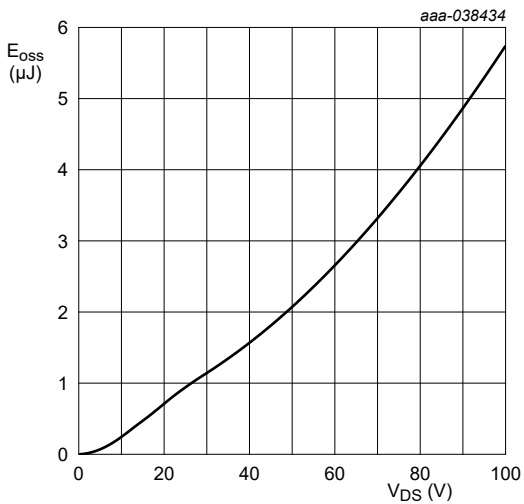


Fig. 15. COSS stored energy as a function of drain-source voltage; typical values

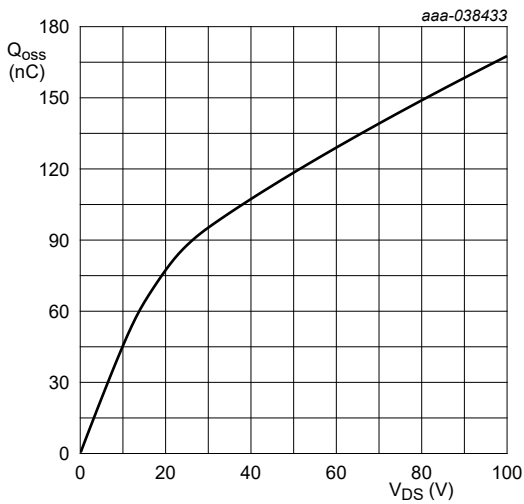


Fig. 16. Output charge as a function of drain-source voltage; typical values

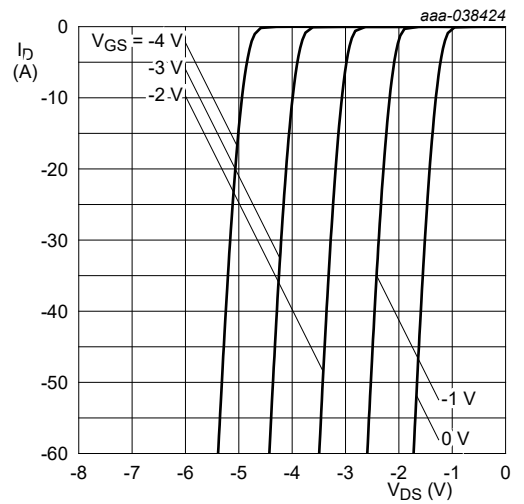
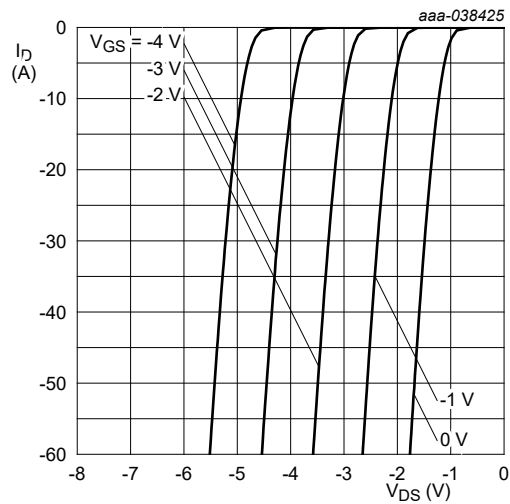


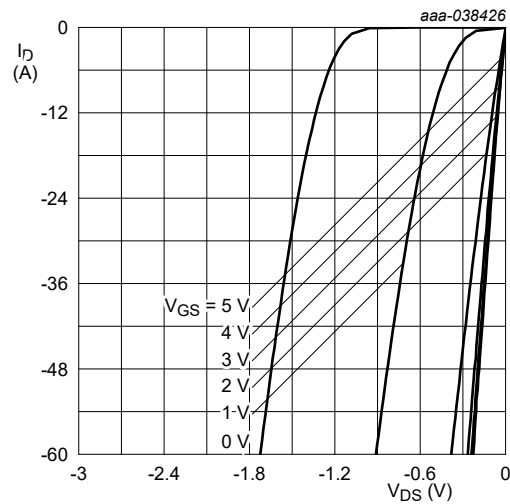
Fig. 17. Source current as a function of source-drain voltage; typical values

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)



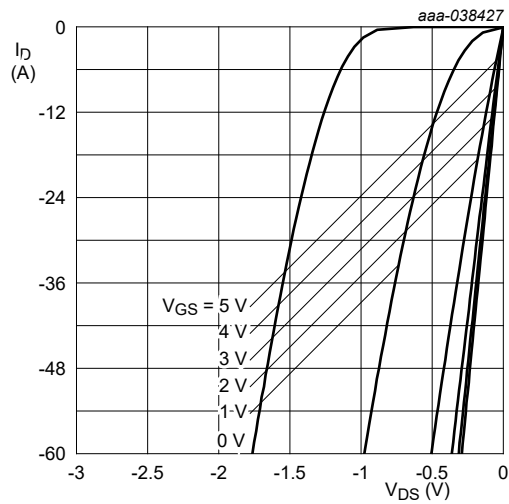
T<sub>j</sub> = 125 °C

Fig. 18. Source current as a function of source-drain voltage; typical values



T<sub>j</sub> = 25 °C

Fig. 19. Source current as a function of source-drain voltage; typical values



T<sub>j</sub> = 125 °C

Fig. 20. Source current as a function of source-drain voltage; typical values

11. Package outline

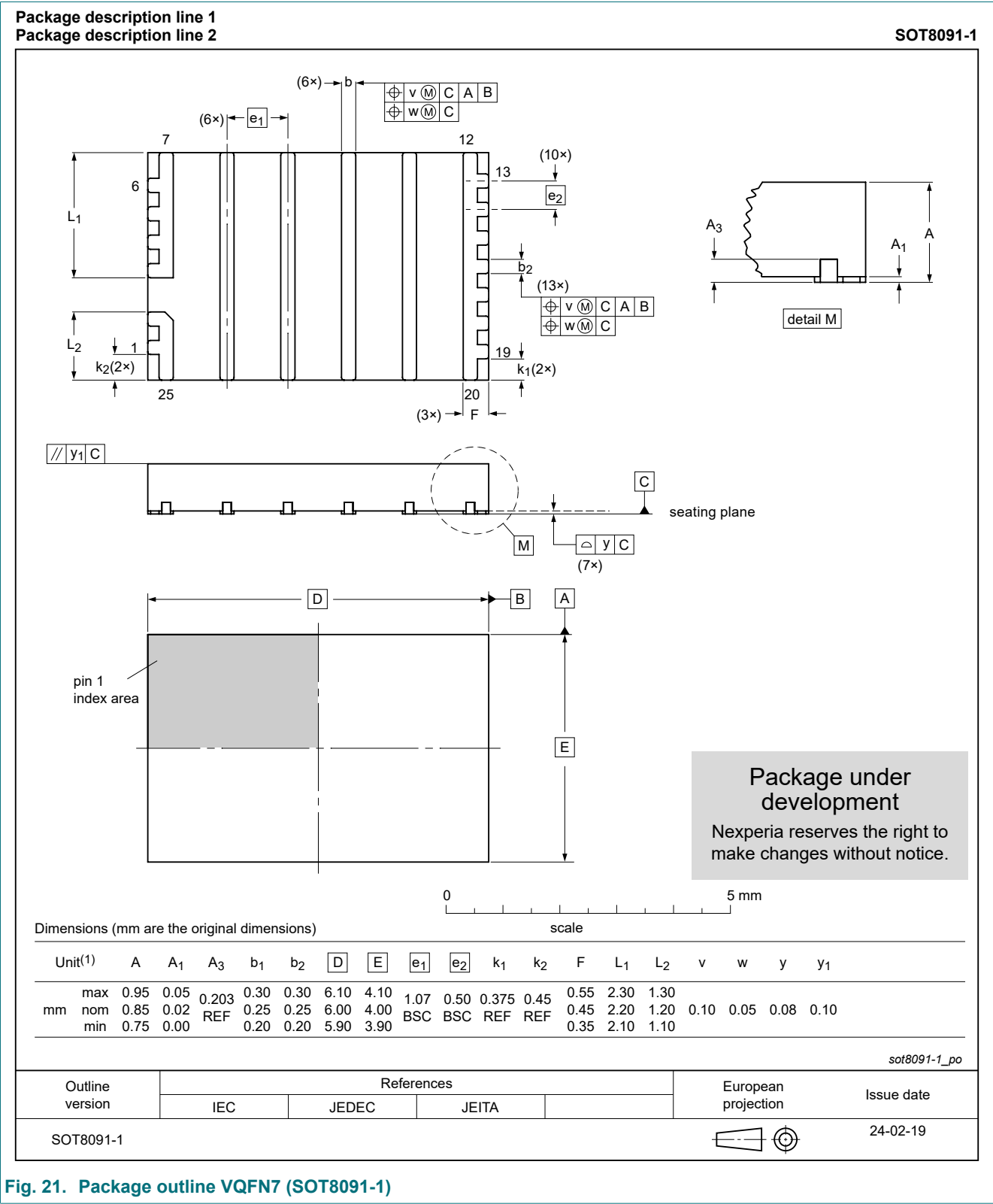


Fig. 21. Package outline VQFN7 (SOT8091-1)



13. Legal information

Data sheet status

| Document status [1][2]         | Product status [3] | Definition                                                                            |
|--------------------------------|--------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

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